



Material Content Data Sheet



Sales Product Name				IPD042P03L3 G		Issued		25. September 2017	
MA#				MA000509186					
Package				PG-TO252-3-311		Weight*		315.42 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.261	1.35	1.35	13509	13509	
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		136		
	non noble metal	iron	7439-89-6	0.143	0.05		454		
	non noble metal	copper	7440-50-8	143.098	45.35	45.41	453670	454260	
	non noble metal	aluminium	7429-90-5	2.561	0.81	0.81	8119	8119	
wire	inorganic material	antimonytrioxide	1309-64-4	1.945	0.62		6166		
encapsulation	plastics	brominated resin	-	2.084	0.66		6607		
	organic material	carbon black	1333-86-4	2.223	0.70		7047		
	plastics	epoxy resin	-	18.755	5.95		59460		
	inorganic material	silicondioxide	60676-86-0	113.919	36.12	44.05	361164	440444	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11857	11857	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	274	275	
solder	non noble metal	tin	7440-31-5	0.067	0.02		213		
	noble metal	silver	7440-22-4	0.084	0.03		266		
	non noble metal	lead	7439-92-1	3.211	1.02	1.07	10179	10658	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		61		
	non noble metal	copper	7440-50-8	19.177	6.08	6.09	60799	60878	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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